

# RD3L03BBG

# Nch 60V 50A Power MOSFET

V <sub>DSS</sub>	60V
R <sub>DS(on)</sub> (Max.)	11.3mΩ
I <sub>D</sub>	±50A
P <sub>D</sub>	50W

### Features

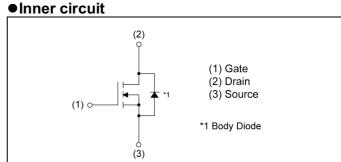
- 1) Low on resistance
- 2) High power package (TO-252)
- 3) Pb-free plating; RoHS compliant
- 4) Halogen free



Outline

DPAK

TO-252



Packaging specifications

	Jing specifications	
	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	16
	Quantity (pcs)	2500
	Taping code	TL1
	Marking	RD3L03BBG

# Application Switching

# ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Para	meter	Symbol	Value	Unit
Drain - Source voltage	$V_{DSS}$	60	V	
Cantinuous drain aurent	Silicon limit (V <sub>GS</sub> =10V)	I <sub>D</sub> *1	±50	Α
Continuous drain current	T <sub>a</sub> = 25°C (V <sub>GS</sub> =10V)	I <sub>D</sub> *2	±35	Α
Pulsed drain current	I <sub>DP</sub> *3	±200	Α	
Gate - Source voltage	$V_{GSS}$	±20	V	
Avalanche current, single p	ulse	l <sub>AS</sub> *4	16.5	Α
Avalanche energy, single p	ulse	E <sub>AS</sub> *4	21	mJ
Power dissipation		P <sub>D</sub> *2	50	W
Junction temperature		T <sub>j</sub>	150	°C
Operating junction and stor	T <sub>stg</sub>	-55 to +150	°C	

### ●Thermal resistance

Parameter	Symbol	Values			Lloit
		Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *2	-	-	2.5	°C/W

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davamatav	Cymah al	Canditions	Values			l limit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	60	-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_i} I_D = 1 \text{mA}$ referenced to 25°C		-	38.9	-	mV/°C
Zero gate voltage drain current	I <sub>DSS</sub>	$I_{DSS}$ $V_{DS} = 60V, V_{GS} = 0V$		-	1	μA
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$	1	-	±100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 1mA$	1.0	-	2.5	V
Gate threshold voltage temperature coefficient	$\frac{\DeltaV_{GS(th)}}{\DeltaT_j}$			-4.7	-	mV/°C
Static drain - source	D *5	V <sub>GS</sub> = 10V, I <sub>D</sub> = 35A	-	8.7	11.3	mO
on - state resistance	R <sub>DS(on)</sub> *5	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 17.5A	-	12.1	16.9	mΩ
Gate resistance	$R_{G}$	-	-	2.0	-	Ω
Forward Transfer Admittance	Y <sub>fs</sub>  *5	V <sub>DS</sub> = 5V, I <sub>D</sub> = 17.5A	9.0	-	-	S

<sup>\*1</sup> Limited by silicon chip capability.

<sup>\*2</sup>  $T_c$ =25°C, Limited only by maximum temperature allowed.

<sup>\*3</sup> Pw  $\leq$  10 $\mu$ s , Duty cycle  $\leq$  1%

<sup>\*4</sup> L  $\simeq$  0.1mH, V<sub>DD</sub> = 30V, R<sub>G</sub> = 25 $\Omega$ , Starting T<sub>j</sub> = 25 $^{\circ}$ C Fig.3-1,3-2

<sup>\*5</sup> Pulsed

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Daramatar	Symbol .	Conditions		Unit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	970	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 30V	-	255	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	24	-	
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DD} \simeq 30V, V_{GS} = 10V$	1	12.0	-	
Rise time	<b>t</b> r*5	I <sub>D</sub> = 17.5A	1	11.0	1	no
Turn - off delay time	t <sub>d(off)</sub> *5	R <sub>L</sub> ≃ 1.72Ω	-	35.0	_	ns
Fall time	<b>t</b> <sub>f</sub> *5	$R_G = 10\Omega$	-	8.6	-	

# • Gate charge characteristics $(T_a = 25^{\circ}C)$

Daramatar	Current el	Conditions		Values			1.1:4	
Parameter	Symbol			Min.	Тур.	Max.	Unit	
Total gate charge	Q <sub>g</sub> *5	$Q_g^{*5}$	O *5	V <sub>GS</sub> = 10V	-	14.0	-	
Total gate charge			$Q_g$	$V_{DD} \simeq 30V$		-	7.1	-
Gate - Source charge	Q <sub>gs</sub> *5	I <sub>D</sub> = 35A	V <sub>GS</sub> = 4.5V	-	2.7	-	nC	
Gate - Drain charge	Q <sub>gd</sub> *5				-	2.1	-	

# ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions		Unit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Continuous forward current	I <sub>S</sub>	T <sub>a</sub> = 25°C	-	-	35	Α
Pulse forward current	I <sub>SP</sub> *3	1 <sub>a</sub> - 25 C	-	-	200	Α
Forward voltage	V <sub>SD</sub> *5	$V_{GS} = 0V, I_{S} = 35A$	-	-	1.2	V
Reverse recovery time	t <sub>rr</sub> *5	I <sub>S</sub> = 35A, V <sub>GS</sub> =0V	-	34	-	ns
Reverse recovery charge	Q <sub>rr</sub> *5	di/dt = 100A/μs	-	36	-	nC

#### • Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

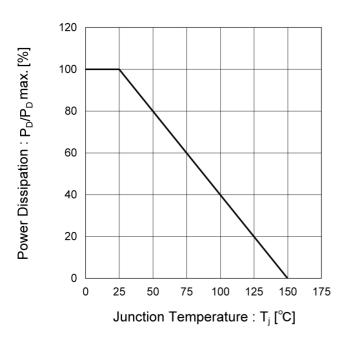
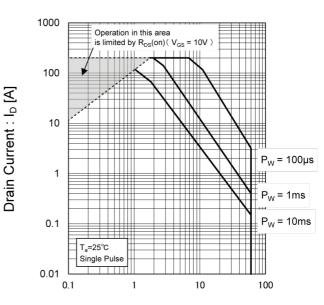


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

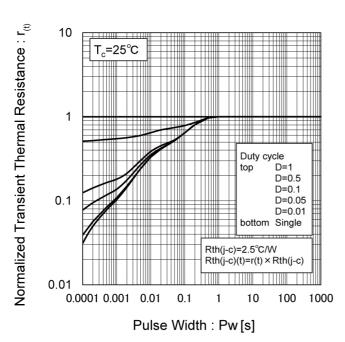
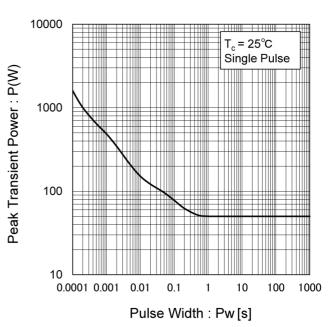
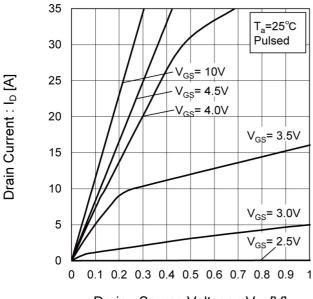


Fig.4 Single Pulse Maximum Power Dissipation



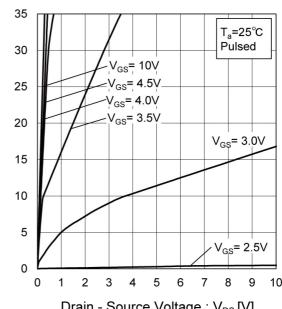
#### Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.6 Typical Output Characteristics(II)



Drain Current : I<sub>D</sub> [A]

Drain - Source Voltage: V<sub>DS</sub>[V]

Fig.7 Breakdown Voltage vs. **Junction Temperature** 

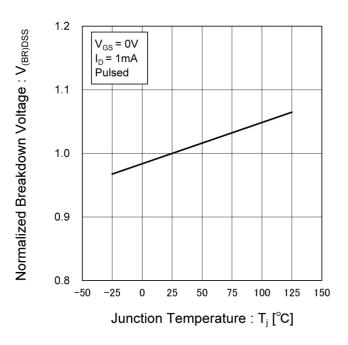
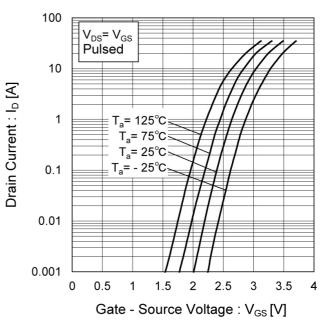


Fig.8 Typical Transfer Characteristics



### • Electrical characteristic curves

Fig.9 Gate Threshold Voltage vs.
Junction Temperature

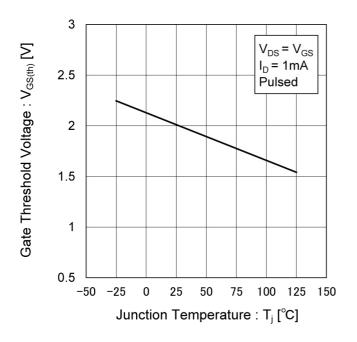


Fig.10 Forward Transfer Admittance vs.
Drain Current

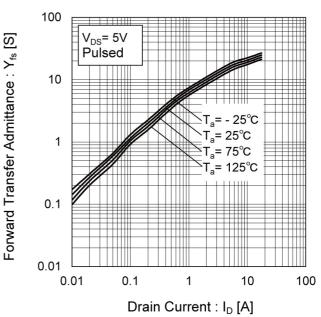


Fig.11 Drain Current Derating Curve

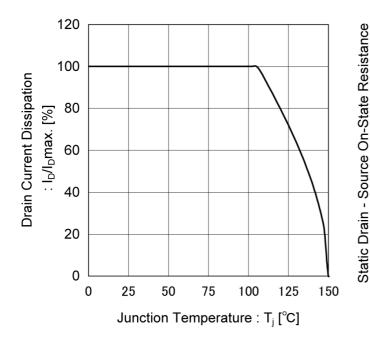
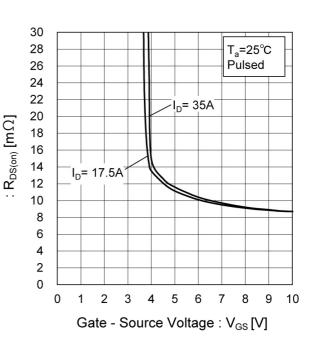


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



### • Electrical characteristic curves

Fig.13 Static Drain - Source On - State
Resistance vs. Junction Temperature

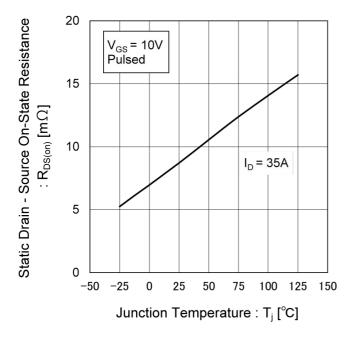


Fig.14 Static Drain - Source On - State
Resistance vs. Drain Current (I)

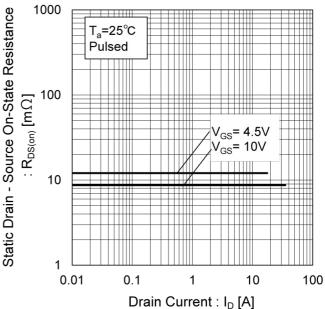


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

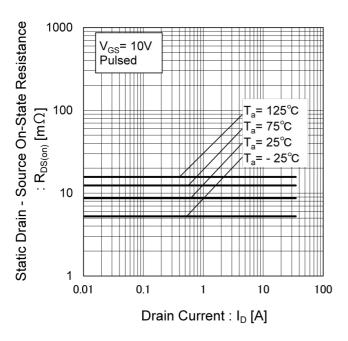
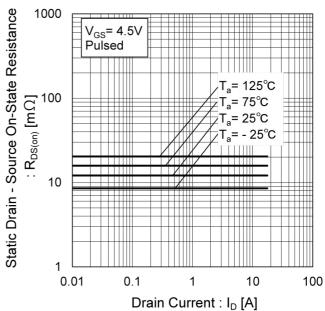
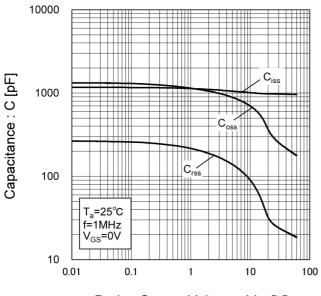


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)



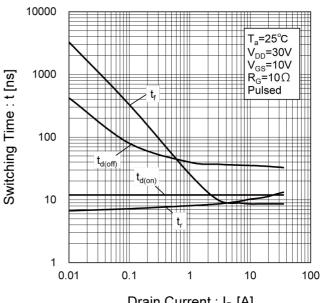
### Electrical characteristic curves

Fig.17 Typical Capacitances vs. Drain - Source Voltage



Drain - Source Voltage: V<sub>DS</sub> [V]

Fig.18 Switching Characteristics



Drain Current: I<sub>D</sub> [A]

Fig.19 Typical Gate Charge

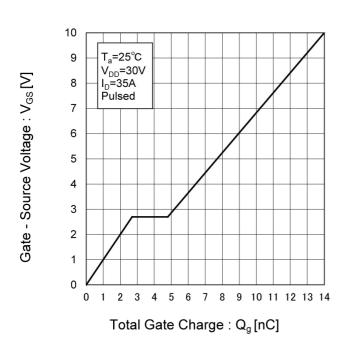
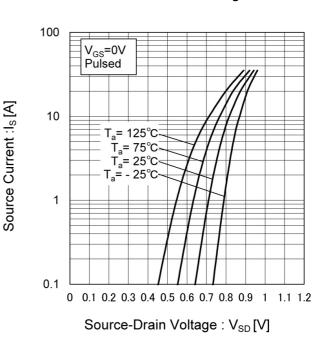


Fig.20 Source Current vs. Source Drain Voltage



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### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

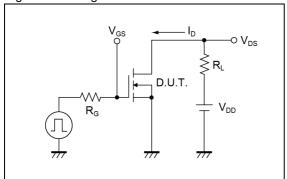


Fig.1-2 Switching Waveforms

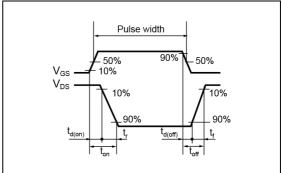


Fig.2-1 Gate Charge Measurement Circuit

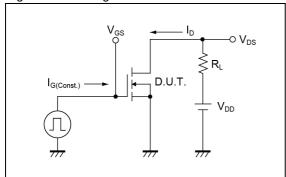


Fig.2-2 Gate Charge Waveform

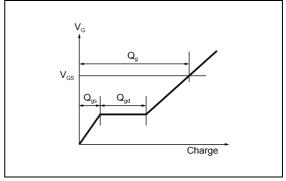


Fig.3-1 Avalanche Measurement Circuit

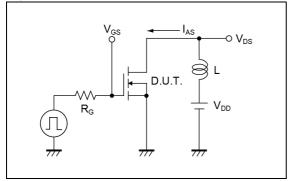
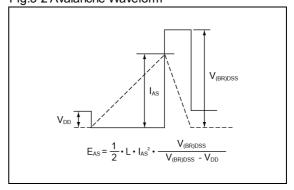
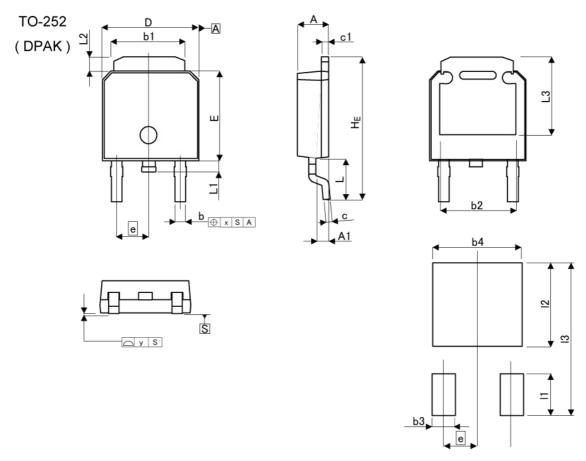


Fig.3-2 Avalanche Waveform



## Dimensions



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIME	TERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	2.20	2.40	0.087	0.094
A1	0.70	1.10	0.028	0.043
b	0.60	0.90	0.024	0.035
b1	5.20	5.50	0.205	0.217
b2	4.	80	0.1	89
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
е	2.	30	0.0	91
E	6.00	6.40	0.236	0.252
HE	9.40	10.40	0.370	0.409
L	2.	90	0.1	14
L1	0.60	1.00	0.024	0.039
L2	0.70	1.30	0.028	0.051
L3	5.	5.30		209
Х	-	0.25	-	0.010
у	-	0.10	, <del>-</del> ,	0.004
DIM	MILIME	TERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b3	- 1	1.15	-	0.045
b4	-	5.55	. <del></del>	0.219
l1	-	2.77	-	0.109
12	-	5.50	-	0.217
13	-	10.40	-	0.409

Dimension in mm/inches



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JÁPAN	USA	EU	CHINA
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CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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